



# Initial Product/Process Change Notification

Document #: IPCN25630Z

Issue Date: 27 Sep 2023

<b>Title of Change:</b>	Carmona Leadframe Consolidation SOIC 14 & 16	
<b>Proposed Changed Material First Ship Date:</b>	08 Nov 2024 or earlier if approved by customer	
<b>Current Material Last Order Date:</b>	N/A <i>Orders received after the Current Material Last Order Date expiration are to be considered as orders for new changed material as described in this PCN. Orders for current (unchanged) material after this date will be per mutual agreement and current material inventory availability.</i>	
<b>Current Material Last Delivery Date:</b>	N/A <i>The Current Material Last Delivery Date may be subject to change based on build and depletion of the current (unchanged) material inventory</i>	
<b>Product Category:</b>	Active components – Integrated circuits	
<b>Contact information:</b>	Contact your local onsemi Sales Office or <a href="mailto:Israel.Villegas@onsemi.com">Israel.Villegas@onsemi.com</a>	
<b>PCN Samples Contact:</b>	Contact your local onsemi Sales Office to place sample order. Sample requests are to be submitted no later than 45 days after publication of this change notification. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.	
<b>Additional Reliability Data:</b>	Contact your local onsemi Sales Office or <a href="mailto:Nhel.Malonzo@onsemi.com">Nhel.Malonzo@onsemi.com</a>	
<b>Type of Notification:</b>	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 6 months prior to implementation of the change. In case of questions, contact < <a href="mailto:PCN.Support@onsemi.com">PCN.Support@onsemi.com</a> >.	
<b>Change Category</b>		
<b>Category</b>	<b>Type of Change</b>	
Process - Assembly	Change in leadframe dimensions	
<b>Description and Purpose:</b>		
Leadframe consolidation resulting in change to flag size dimension.		
	<b>Before</b>	<b>After</b>
<b>Leadframe</b>	SOIC 14L Set A Flag Size (mils) 100x160, 100x150, 90x130, 90x90, 90x130	Flag Size 100x160mils
	SOIC 14 Set B Flag Size (mils) 70x70, 55x63, 37x37, 55x63	Flag Size 70x70mils
	SOIC 16 Flag size (mils) 70x70, 90x90, 90x130, 94x100, 100x150	Flag size 100x150mils
There are no product material changes as a result of this change.		
There is no product marking change as a result of this change. Change in leadframe flag size is identifiable by date code.		
<b>Reason / Motivation for Change:</b>	Process/Materials Change	
<b>Anticipated impact on fit, form, function, reliability, product safety or manufacturability:</b>	The device will be qualified and validated based on the same Product Specification. No anticipated impacts.	



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<b>Sites Affected:</b>			
<b>onsemi Sites</b>		<b>External Foundry/Subcon Sites</b>	
onsemi Carmona, Philippines		None	
<b>Marking of Parts/ Traceability of Change:</b>		Change in leadframe can be identified by date code.	
<b>Reliability Data Summary:</b>			
QV DEVICE NAME: NLV14014BDR2G_NLV14094BDR2G			
RMS: TBD			
PACKAGE: SOIC 16			
Test	Specification	Condition	Interval
High Temperature Storage Life	JESD22-A103	Ta= 150°C	1008 hrs
Preconditioning	J-STD-020 JESD-A113	MSL 1 @ 260 °C	
Temperature Cycling	JESD22-A104	Ta= -65°C to +150°C	500 cyc
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
Solderability	JSTD002	Ta = 245°C, 5 sec	
Physical Dimensions	JESD22-B100 & B108		
QV DEVICE NAME: NLV14572UBDR2G_NCV1413BDR2G			
RMS: TBD			
PACKAGE: SOIC 16			
Test	Specification	Condition	Interval
High Temperature Storage Life	JESD22-A103	Ta= 150°C	1008 hrs
Preconditioning	J-STD-020 JESD-A113	MSL 1 @ 260 °C	
Temperature Cycling	JESD22-A104	Ta= -65°C to +150°C	500 cyc
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
Solderability	JSTD002	Ta = 245°C, 5 sec	
Physical Dimensions	JESD22-B100 & B108		
QV DEVICE NAME: NCV20034DR2G NCV20074DR2G - HAST			
RMS:			
PACKAGE: SOIC 14			
Test	Specification	Condition	Interval
High Temperature Storage Life	JESD22-A103	Ta= 150°C	1008 hrs
Preconditioning	J-STD-020, JESD-A113	MSL 1 @ 260°C	
Temperature Cycling	JESD22-A104	Ta= -65°C to +150°C	500 cyc
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs



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Solderability	JSTD002	Ta = 245°C, 5 sec	
Physical Dimensions	JESD22-B100 and B108		

QV DEVICE NAME: NLV14012BDR2G

RMS:

PACKAGE: SOIC 14

Test	Specification	Condition	Interval
High Temperature Storage Life	JESD22-A103	Ta= 150°C	1008 hrs
Preconditioning	J-STD-020, JESD-A113	MSL 1 @ 260°C	
Temperature Cycling	JESD22-A104	Ta= -65°C to +150°C	500 cyc
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
Solderability	JSTD002	Ta = 245°C, 5 sec	
Physical Dimensions	JESD22-B100 and B108		

QV DEVICE NAME: SCV209D2R2G / LMV824DR2G

RMS: TBD

PACKAGE: SOIC 14

Test	Specification	Condition	Interval
High Temperature Storage Life	JESD22-A103	Ta= 150°C	1008 hrs
Preconditioning	J-STD-020, JESD-A113	MSL 3 @ 260°C	
Temperature Cycling	JESD22-A104	Ta= -65°C to +150°C	500 cyc
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
Solderability	JSTD002	Ta = 245°C, 5 sec	
Physical Dimensions	JESD22-B100 and B108		

QV DEVICE NAME: NCV7420D26R2G (0C616-004)

RMS: TBD

PACKAGE: SOIC 14

Test	Specification	Condition	Interval
High Temperature Storage Life	JESD22-A103	Ta= 175°C	1008 hrs
Preconditioning	J-STD-020, JESD-A113	MSL 2 @ 260°C	
Temperature Cycling	JESD22-A104	Ta= -65°C to +175°C	500 cyc
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
Solderability	JSTD002	Ta = 245°C, 5 sec	
Physical Dimensions	JESD22-B100 and B108		



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QV DEVICE NAME: NCV7343D21R2G (0N343-003)

RMS: TBD

PACKAGE: SOIC 14

Test	Specification	Condition	Interval
High Temperature Storage Life	JESD22-A103	Ta= 175°C	1008 hrs
Preconditioning	J-STD-020, JESD-A113	MSL 2 @ 260°C	
Temperature Cycling	JESD22-A104	Ta= -55°C to +150°C	2000 cyc
Highly Accelerated Stress Test	JESD22-A110	110°C, 85% RH, 18.8psig, bias	264 hrs
Unbiased Highly Accelerated Stress Test	JESD22-A118	110°C, 85% RH, 18.8psig, unbiased	264 hrs
Solderability	JSTD002	Ta = 245°C, 5 sec	
Physical Dimensions	JESD22-B100 and B108		

QV DEVICE NAME: NCV2902DR2G

RMS: TBD

PACKAGE: SOIC 14

Test	Specification	Condition	Interval
High Temperature Storage Life	JESD22-A103	Ta= 150°C	1008 hrs
Preconditioning	J-STD-020, JESD-A113	MSL 1 @ 260°C	
Temperature Cycling	JESD22-A104	Ta= -65°C to +150°C	500 cyc
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
Solderability	JSTD002	Ta = 245°C, 5 sec	
Physical Dimensions	JESD22-B100 and B108		

QV DEVICE NAME: NLV14013BDR2G

RMS: TBD

PACKAGE: SOIC 14

Test	Specification	Condition	Interval
High Temperature Storage Life	JESD22-A103	Ta= 150°C	1008 hrs
Preconditioning	J-STD-020, JESD-A113	MSL 1 @ 260°C	
Temperature Cycling	JESD22-A104	Ta= -65°C to +150°C	500 cyc
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
Solderability	JSTD002	Ta = 245°C, 5 sec	
Physical Dimensions	JESD22-B100 and B108		

Estimated date for qualification completion: 29 March 2024



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## Electrical Characteristics Summary:

Electrical characteristics are not impacted.

## List of Affected Parts:

**Note:** Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

Current Part Number	New Part Number	Qualification Vehicle
NLV14013BDR2G	NA	NLV14013BDR2G
NCV3843BVDR2G	NA	NLV14013BDR2G
NLV14066BDR2G	NA	NLV14013BDR2G
NLV14106BDR2G	NA	NLV14013BDR2G
NLV14541BDR2G	NA	NLV14013BDR2G
NCV33079DR2G	NA	NCV2902DR2G
NCV7343D21R2G	NA	NCV7343D21R2G_ON343-003
NCV7343D20R2G	NA	NCV7343D21R2G_ON343-003
NCV7420D24R2G	NA	NCV7420D26R2G_OC616-004
NCV7420D26R2G	NA	NCV7420D26R2G_OC616-004
NCV7703CD2R2G	NA	NCV7343D21R2G_ON343-003
NCV7721D2R2G	NA	NCV7343D21R2G_ON343-003
NCV33204DR2G	NA	NCV2902DR2G
NCV33274ADR2G	NA	NCV2902DR2G
CS45008DR14G	NA	SCV209D2R2G_LMV824DR2G
CS3361YDR14G	NA	SCV209D2R2G_LMV824DR2G
NCV7430D20R2G	NA	NCV7420D26R2G_OC616-004
NCV7748D2R2G	NA	NCV7343D21R2G_ON343-003
NLV14011BDR2G	NA	NLV14012BDR2G
NLV14012BDR2G	NA	NLV14012BDR2G
NCV20034DR2G	NA	NCV20034DR2G_NCV20074DR2G
NLV14572UBDR2G	NA	NLV14572UBDR2G
NLV14556BDR2G	NA	NLV14572UBDR2G_NCV1413BDR2G
NLV14027BDR2G	NA	NLV14572UBDR2G_NCV1413BDR2G
NLV14174BDR2G	NA	NLV14572UBDR2G_NCV1413BDR2G
NLV14014BDR2G	NA	NLV14014BDR2G
NCV494BDR2G	NA	NLV14014BDR2G_NLV14094BDR2G



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NLV14051BDR2G	NA	NLV14014BDR2G_NLV14094BDR2G
NLV14052BDR2G	NA	NLV14014BDR2G_NLV14094BDR2G
NLV14551BDR2G	NA	NLV14014BDR2G_NLV14094BDR2G
NLV14538BDR2G	NA	NLV14014BDR2G_NLV14094BDR2G
NLV14528BDR2G	NA	NLV14014BDR2G_NLV14094BDR2G
NLV14053BDR2G	NA	NLV14014BDR2G_NLV14094BDR2G
NLV14017BDR2G	NA	NLV14014BDR2G_NLV14094BDR2G
NLV14521BDR2G	NA	NLV14014BDR2G_NLV14094BDR2G
NLV14040BDR2G	NA	NLV14014BDR2G_NLV14094BDR2G
NLV14020BDR2G	NA	NLV14014BDR2G_NLV14094BDR2G
NLV14029BDR2G	NA	NLV14014BDR2G_NLV14094BDR2G
NLV14503BDR2G	NA	NLV14014BDR2G_NLV14094BDR2G
NLV14516BDR2G	NA	NLV14014BDR2G_NLV14094BDR2G
NLV14504BDR2G	NA	NLV14014BDR2G_NLV14094BDR2G
NLV14022BDR2G	NA	NLV14014BDR2G_NLV14094BDR2G
NLV14015BDR2G	NA	NLV14014BDR2G_NLV14094BDR2G
NLV14043BDG	NA	NLV14014BDR2G_NLV14094BDR2G
NLV14043BDR2G	NA	NLV14014BDR2G_NLV14094BDR2G
NLV14044BDR2G	NA	NLV14014BDR2G_NLV14094BDR2G
NLV14094BDR2G	NA	NLV14094BDR2G
NLV14021BDR2G	NA	NLV14014BDR2G_NLV14094BDR2G
NLV14512BDR2G	NA	NLV14014BDR2G_NLV14094BDR2G
NLV14028BDR2G	NA	NLV14014BDR2G_NLV14094BDR2G
NLV14532BDR2G	NA	NLV14014BDR2G_NLV14094BDR2G
NLV14585BDR2G	NA	NLV14014BDR2G_NLV14094BDR2G
NLV14543BDR2G	NA	NLV14014BDR2G_NLV14094BDR2G
SCV7703CD2R2G	NA	NCV7343D21R2G_0N343-003